

CURABLE RESIN COMPOSITION, ELECTRONIC COMPONENT DEVICE, AND
PRODUCTION METHOD FOR ELECTRONIC COMPONENT DEVICE

ABSTRACT

A curable resin composition that satisfies any one of the following (1), (2) or (3):

(1) comprising a curable resin component, triphenylphosphine oxide, and a filler, the triphenylphosphine oxide being included in the curable resin composition in an amount of 0.3% by mass or more;

(2) comprising a curable resin component, triphenylphosphine oxide, and a filler, the triphenylphosphine oxide being included in the curable resin composition in an amount of less than 0.3% by mass;

(3) comprising a curable resin component, triphenylphosphine oxide, and a filler, the filler including cristobalite.